

IN THE CLAIMS:

Please amend the claims as follows:

1. (Previously presented) Apparatus for processing multiple semiconductor wafers, the apparatus comprising:
 - a transfer chamber;
 - a first processing chamber mounted in fixed relation to the transfer chamber and having a first wafer-holding platform with a center;
 - a second processing chamber mounted in adjustable relation to the transfer chamber and to the first chamber and having a second wafer-holding platform with a center, wherein the first and second processing chambers are disposed on a common side of the transfer chamber;
 - a robot rotatably mounted within the transfer chamber and having first and second wafer-holding arms configured parallel to each other for inserting a pair of wafers simultaneously into the first and second chambers; and
 - a mechanism disposed between the second chamber and the transfer chamber, adapted to selectively position the second chamber relative to the robot arms such that the wafers are centered and placed with a preselected degree of accuracy onto the respective platforms for efficient processing of the wafers.
2. (Previously presented) The apparatus of claim 1 wherein the first and second chambers are closely spaced self-contained units supported in cantilever fashion from a wall of the transfer chamber, the chambers and the platforms being adapted to simultaneously process wafers using edge purging.
3. (Currently amended) Apparatus for processing multiple semiconductor wafers, the apparatus comprising:
 - a transfer chamber;
 - a first processing chamber mounted in known relation to the transfer chamber and having a first wafer-holding platform with a center;

a second processing chamber having a second wafer-holding platform with a center, wherein the first and second processing chambers are disposed on a common side of the transfer chamber;

a mechanism for adjustably mounting the second chamber in relation to the first chamber and to the transfer chamber, wherein the mechanism is adapted to selectively providing a plurality of position adjustments for the second chamber in relation to the transfer chamber; and

a robot rotatably mounted within the transfer chamber and having first and second wafer-holding arms configured parallel to each other for inserting a pair of wafers simultaneously into the first and second chambers and for placing the wafers accurately centered over the respective platforms,

wherein the mechanism selectively positions the second chamber is adjustable relative to the robot arms such that the wafers are centered and placed with a preselected degree of accuracy onto the respective platforms for efficient processing of the wafers.

4. (Previously presented) The apparatus of claim 3 wherein the mechanism comprises a bellows assembly positioned between the transfer chamber and the second chamber, providing a wafer passageway between the chambers while maintaining a hermetic seal.

5. (Previously presented) The apparatus of claim 3 wherein the mechanism comprises:

a first plate fastened to a wall of the transfer chamber;

a second plate fastened to a wall of the second chamber;

a bellows assembly sealed between the plates, the bellows assembly responds to relative movement between the plates and provides a hermetically sealed wafer passageway between the chambers; and

means for securing the relative positions of the plates once adjustments thereto have been effected.

6. (Previously presented) The apparatus of claim 5 wherein the first and second plates are hinged together along a bearing line such that position adjustments thereto can be made in "X", "Y" and "Z" directions.
7. (Currently amended) Apparatus for processing at least two semiconductor wafers simultaneously, the apparatus comprising:
- a transfer chamber;
 - a load-lock chamber adjacent the transfer chamber;
 - a first processing chamber mounted in known relation to the transfer chamber and having a first wafer-holding platform with a center;
 - a second processing chamber having a second wafer-holding platform with a center, wherein the first and second processing chambers are disposed on a common side of the transfer chamber;
 - a means disposed between the second chamber and the transfer chamber, adapted to selectively position ~~for adjustably positioning~~ the second chamber in relation to the first chamber and to the transfer chamber, providing relative movement therebetween, and also providing a wafer passageway therethrough while maintaining an a hermetic seal; and
 - a robot rotatably mounted around a center axis within the transfer chamber and having first and second wafer-holding arms configured parallel to each other for withdrawing a pair of wafers from the load-lock chamber and inserting the pair of wafers simultaneously into the first and second chambers and for positioning both of the wafers with a preselected degree of accuracy over the respective platforms.
8. (Previously presented) The apparatus of claim 7 further comprising additional processing chambers corresponding respectively to the first and second chamber, the additional chambers being mounted relative to the load-lock chamber in ways respectively like those of the first and second chambers.
9. (Currently amended) Apparatus for processing a pair of semiconductor wafers simultaneously, the apparatus comprising:

a transfer chamber;
a load-lock chamber adjacent the transfer chamber;
a first processing chamber mounted in fixed relation to the transfer chamber and having a first wafer-holding platform with a center;

a second processing chamber having a second wafer-holding platform with a center, wherein the first and second processing chambers are disposed on a common side of the transfer chamber;

mechanical means for adjustably mounting the second chamber in relation to the first chamber and to the transfer chamber and adapted to selectively position the second chamber in relation to the transfer chamber; the mechanical means supporting the second chamber against the transfer chamber in cantilever fashion and having a bellows assembly positioned between the transfer chamber and the second chamber to provide for relative movement thereof and to provide a wafer passageway between the respective chambers while maintaining a hermetic seal;

a slit valve adjacent the passageway for hermetically sealing the transfer chamber from the second chamber; and

a remotely controlled robot rotatably mounted around a center axis within the transfer chamber and having first and second wafer-holding arms configured parallel to each other for withdrawing a pair of wafers from the load-lock chamber and inserting the pair of wafers simultaneously into the first and second chambers and for positioning both of the wafers to a preselected degree of accuracy over the respective platforms, the second chamber is adjustable by the mechanical means relative to the robot arms and the center axis such that the wafers are centered and placed with the preselected degree of accuracy onto the respective platforms for efficient processing of the wafers.

10. (Previously presented) The apparatus of claim 9 wherein the mechanical means provides for adjusting the position of the second chamber in "X", "Y", and "Z" directions, and for thereafter rigidly fastening in place such position.

11. (Currently amended) An apparatus for processing multiple semiconductor wafers, comprising:

a transfer chamber;
at least one pair of processing chambers disposed about the transfer chamber,
wherein each pair of processing chambers comprises:
a first processing chamber mounted in known relation to the transfer chamber;
and
a second processing chamber adjustably mounted to the transfer chamber,
wherein the first and second processing chambers are disposed on a common side of
the transfer chamber;
a mechanism disposed between the second processing chamber and the
transfer chamber, adapted to selectively position for positioning the second processing
chamber in relation to the first processing chamber and in relation to the transfer
chamber; and
a robot mounted within the transfer chamber for inserting a pair of wafers
simultaneously into the first and second processing chambers.

12. (Previously presented) The apparatus of claim 11, wherein the second chamber
is adjustable relative to the robot such that the wafers are centered and placed within a
preselected degree of accuracy within the first and the second processing chambers.

13. (Previously presented) The apparatus of claim 11, wherein the mechanism
comprises a bellows assembly disposed between a first plate and a second plate.

14. (Previously presented) The apparatus of claim 11, wherein the first plate is
connectable to a side wall of the transfer chamber and the second plate is connectable
to a side wall of the second chamber.

15. (Previously presented) The apparatus of claim 14, wherein the bellows assembly
allows a spacial relationship of the sidewalls of the transfer chamber and the second
chamber to be adjusted thereby positioning a wafer platform within the second chamber
in alignment with a wafer platform within the first chamber.

16. (Previously presented) The apparatus of claim 15, wherein the robot accurately centers the wafers over the respective platforms when the second chamber is adjusted in relation to the transfer chamber and the first chamber.
17. (Previously presented) An apparatus for processing multiple semiconductor wafers, comprising:
- a transfer chamber;
 - at least one pair of processing chambers disposed about a common side of the transfer chamber, wherein each pair of processing chambers comprises:
 - a first processing chamber disposed in known relation about the transfer chamber;
 - a second processing chamber adjustably disposed about the transfer chamber;
 - an adjusting mechanism for positioning the second processing chamber relative to the transfer chamber and the first processing chamber;
 - a bellows assembly disposed between the second processing chamber and the transfer chamber and adapted to respond to movement of the second processing chamber in relation to the transfer chamber; and
 - a robot mounted within the transfer chamber adapted to insert a pair of wafers simultaneously into the first and second processing chambers.
18. (Previously presented) The apparatus of claim 17, wherein the bellows assembly responds to the second processing chamber being positioned in relation to the first processing chamber and in relation to the transfer chamber.
19. (Previously presented) The apparatus of claim 17, wherein the bellows assembly provides a hermetically sealed wafer passageway between the second processing chamber and the transfer chamber.
20. (Previously presented) The apparatus of claim 17, wherein the adjusting mechanism allows angular and longitudinal coordinates of a center of a platform within

the second chamber to be aligned with angular and longitudinal coordinates of a center of a platform within the first chamber.

21. (Previously presented) The apparatus of claim 17, wherein the robot is rotatable within the transfer chamber so that the pairs of wafers can be inserted into or withdrawn from the at least one pair of processing chambers.

22. (Previously presented) The apparatus of claim 17, wherein the robot includes at least one pair of spaced apart and vertically aligned arms.

23. (Previously presented) The apparatus of claim 22, wherein the robot arms are extendable along respective longitudinal, parallel axes.

24. (Previously presented) An apparatus for processing multiple semiconductor wafers, comprising:

- a transfer chamber;

- at least one pair of processing chambers disposed about a common side of the transfer chamber, wherein each pair of processing chambers comprises:

- a first processing chamber disposed in known relation about the transfer chamber;

- a second processing chamber adjustably disposed about the transfer chamber;
- and

- a bellows assembly disposed between the second processing chamber and the transfer chamber;

- a mechanism in communication with the bellows assembly adapted to position the second processing chamber relative to the first processing chamber; and

- a robot having horizontal arms and mounted within the transfer chamber for inserting a pair of wafers simultaneously into the first and second processing chambers, the robot having at least two arms extendable along respective longitudinal, parallel axes.

25. (Original) The apparatus of claim 1, wherein the mechanism comprises a bellows assembly positioned between the transfer chamber and the second chamber, providing a wafer passageway between the chambers while maintaining a hermetic seal.
26. (Original) The apparatus of claim 1, wherein the mechanism comprises:
a first plate fastened to a wall of the transfer chamber;
a second plate fastened to a wall of the second chamber;
a bellows assembly sealed between the plates, allowing relative movement between the plates and a hermetically sealed wafer passageway between the chambers; and
means for securing the relative positions of the plates.
27. (Original) The apparatus of claim 26, wherein the first and second plates are hinged together along a bearing line such that position adjustments thereto can be made in "X", "Y" and "Z" directions.
28. (Original) The apparatus of claim 25, wherein the bellows assembly maintains a gas tight seal as the mechanism positions the second processing chamber in relation to the first processing chamber and the transfer chamber.
29. (Original) The apparatus of claim 26, wherein the bellows assembly maintains a gas tight seal as the mechanism positions the second processing chamber in relation to the first processing chamber and the transfer chamber.
30. (Original) The apparatus of claim 1, wherein the mechanism adjusts angular and longitudinal coordinates of the center of the platform within the second chamber relative to angular and longitudinal coordinates of the center of the platform within the first chamber.

Please add the following new claims:

31. (New) An apparatus for processing multiple semiconductor wafers, comprising:

a transfer chamber;

at least one pair of processing chambers disposed about a common side of the transfer chamber, wherein each pair of processing chambers comprises:

a first processing chamber disposed in known relation about the transfer chamber; and

a second processing chamber adjustably disposed about the transfer chamber, wherein the second processing chamber comprises:

a first plate fastened to a wall of the transfer chamber;

a second plate fastened to a wall of the second processing chamber;

a bellows assembly sealed between the first and second plates;

and

at least one spring disposed between the first and second plates;

and

a robot having horizontal arms and mounted within the transfer chamber for inserting a pair of wafers simultaneously into the first and second processing chambers, the robot having at least two arms extendable along respective longitudinal, parallel axes.

32. (New) The apparatus of claim 31, wherein the at least one spring comprises a pair of springs each disposed adjacent a lower corner of the first and second plates.